



Atomic Layer Deposition of Functional Materials

Guest Editor:

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submissions:

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Message from the Guest Editor

Dear Colleagues,

Atomic Layer Deposition (ALD) has become a robust industry tool for functional thin films growth, and a powerful technique to produce novel thin film materials in a research context. Within the ALD community, there still seem to be many avenues for innovation and optimization as the technique matures and diversifies.

In this Special Issue of *Materials*, the focus is to present new developments for Functional Materials growth by ALD. This could include: precursor design, simulation and modeling, novel materials deposition and characterization (multi-component alloys, ferroelectrics, nitrides, metals, 2D materials), and innovations with tool design.

It is my pleasure to invite you to submit a manuscript for this Special Issue. Full papers, communications, and reviews are all welcome.

Dr. Peter J. King
Guest Editor





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Editor-in-Chief

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Message from the Editor-in-Chief

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